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1. Name of conveying party(ies):

Hirotaka MORITA
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2. Name and Address of receiving party(ies):

FUJITSU LIMITED
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3. Nature of conveyance:

X Assignment ___ Merger
___ Security Agreement ___ Change of Name
___ Other: ____________________
Execution Date(s): November 22, 2004

4. Application number(s) or patent number(s):

☒ This document is being filed together with a new application:
(a) The execution date(s) of the application is/are: November 22, 2004
(b) The title is: LAYOUT METHOD FOR SEMICONDUCTOR INTEGRATED CIRCUIT, LAYOUT PROGRAM FOR SEMICONDUCTOR INTEGRATED CIRCUIT AND LAYOUT SYSTEM FOR SEMICONDUCTOR INTEGRATED CIRCUIT

OR

☐ This document is being filed after filing of the application:
(a) Patent Application No(s). ___/______, filed ____________; or
(b) Patent No(s). , issued .

5. Name and address of party to whom correspondence concerning document should be mailed:

STAAS & HALSEY LLP Our Docket: 1460.1050
Attention: H. J. Staas
1201 New York Ave., N.W., Suite 700
Washington, D.C. 20005

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).................... ($ 40.00 per Assignment)

X Enclosed
___ Authorized to be charged to deposit account.

8. Deposit Account No.: 19-3935 (Any underpayment is authorized to be charged to this Deposit Account) (Attach duplicate copy of this page if paying by deposit account)

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

H. J. Staas, Reg. No. 22,010 December 29, 2004

Name of Person Signing Signature Date

Total number of pages including cover sheet: 2

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U.S. ASSIGNMENT

S&H 1/00

IN CONSIDERATION of the sum of One Dollar ($1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by
(Insert Name(s) & Address(es) of ASSIGNEE(S))

FUJITSU LIMITED
1-1, Kamikodanaka 4-Chome, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8588 Japan

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled
(Title of Invention)
LAYOUT METHOD FOR SEMICONDUCTOR INTEGRATED CIRCUIT, LAYOUT PROGRAM FOR SEMICONDUCTOR INTEGRATED CIRCUIT AND LAYOUT SYSTEM FOR SEMICONDUCTOR INTEGRATED CIRCUIT

relating to International Patent Application PCT/JP____/__________ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(a) executed on ______________________; *(Insert date of execution of application, if not concurrent)*

(b) filed on ______________________,

Serial No. ____/____________________;

Any registered attorney of STAAS & HALSEY LLP, 700 Eleventh Street, N.W., Washington, D.C. 20001 (202/434-1500) is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Typed Name & Signature of Inventor(s))	*(Date)*	*(Typed Name & Signature of Witness(es))*
1) 森田浩貴 Hirotaka Morita	Nov. 22, 2004	遠山悦子 Etsuko Tohyama
2) 深澤真治 Shinji Fukasawa	Nov 22, 2004	遠山悦子 Etsuko Tohyama
3)		
4)		
5)		